



## PCB Inspection System VT-S530

Omron's 3D-SJI (Solder Joint Inspection)  
Ensuring High-quality Products  
in an Efficient Manufacturing Environment

High-Resolution Model



### VT-S530



### PCB Inspection System (AOI) Lineup



Support for Post Placement  
VT-S500



Best Sales in Automotive Industry  
VT-S730



Advanced & High-speed  
VT-S730-H

# Omron's 3D-SJI (Solder Joint Inspection)

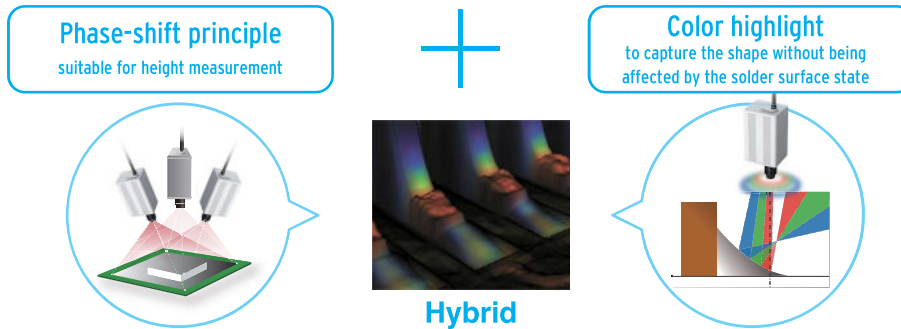
Materializes quantitative inspection of solder joint and implementation, while minimizing risks of overlooking unknown defects by the quality product criteria inspection based on the standards, contributing to vertical startup of inspection.

POINT 1

## 3D reconstruction of solder and components

### Hybrid 3D-SJI

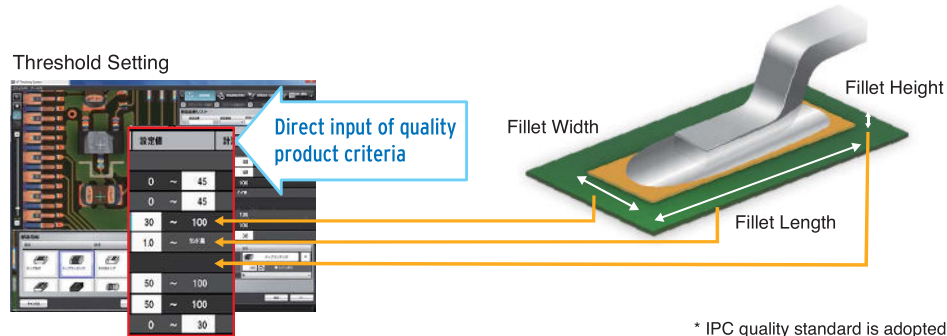
Conducts optimal inspection to suit items to be inspected by combining 3D and 2D technologies.



POINT 2

## Quantitative inspection utilizes quality criteria based on International Standards\*

Contributing to quality control that conforms to International Standards, including IATF (ISO/TS) 16949.



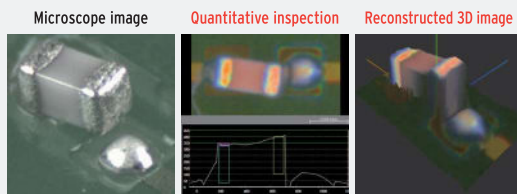
POINT 3

## Materialization of maximum quality inspection with minimum man-hour

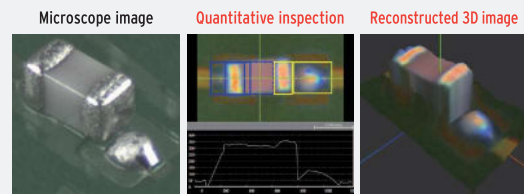
Traditional models	Omron's 3D-SJI S Series
<p>Continuous adjustment is required with each lot fluctuation or new defect occurrence. This model requires continuous debugging.</p> <p>Traditional Difficult to reduce man-hours Required inspection quality Quality fluctuation</p> <p>Defects may be overlooked if all defect conditions are not specified. The number of false calls will not decrease if there is a setting defect.</p>	<p>Automation has reduced man hours required for initial program creation time. Quantitative "quality criteria" based on 3D reconstruction has substantially reduced man hours required for debugging.</p> <p>Omron's "Quality Criteria" Sustaining Stable Inspection Required inspection quality Reduction of man-hours Vertical Startup</p> <p>Only inspected items that meet or exceed the Quality Criteria are passed. The rest are rejected as defects.</p> <p>Defect Pass Defect</p> <p>Reduction of man-hours required for initial program creation.</p> <p>Lands are automatically extracted from a bare board and Component Windows are auto-generated based on the height information.</p>

## Example Defects

Lifted micro component (0603) defect



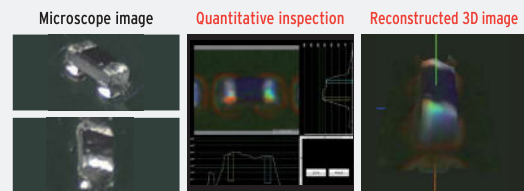
Micro component (0603) insufficient solder wetting defect



Micro component (0402) offset defect



Micro component (0402) inclination defect



Flow solder/insertion component inspection examples



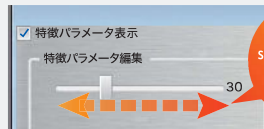
Micro solder ball inspection example



## Whole PCB surface inspection

Detecting foreign objects accurately is achieved through combining 3D (height) and 2D (area) measurements on the entire PCB surface. (Lands without solder can be excluded from the inspection)

検査基準	検査項目	設定値
異物	長短径比 (%)	0 - 30
	面積 (mm <sup>2</sup> )	0 - 0.04
	面積 (mm <sup>2</sup> )	0 - 0.1
	高さ (mm)	0 - 0.1



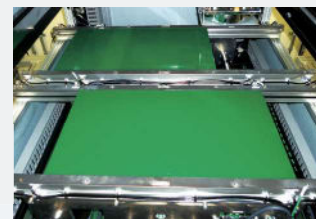
Detection sensitivity can be easily adjusted by the slider

Foreign object (0402 scattered chip) detection example

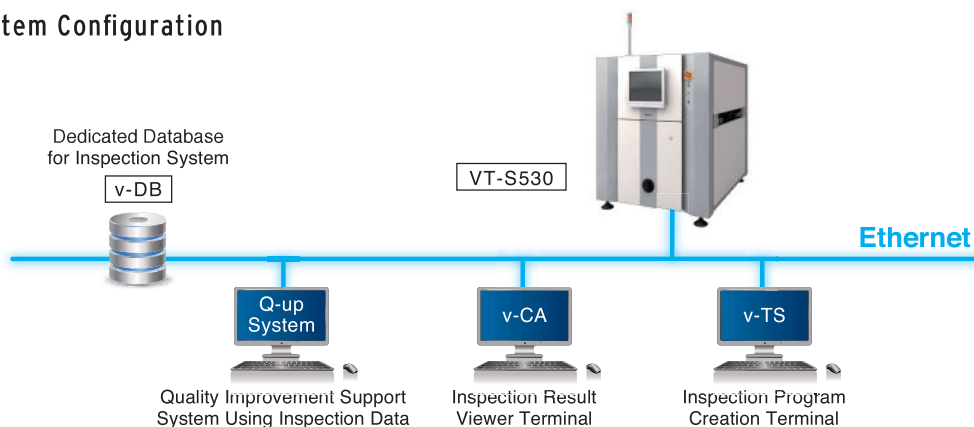


## High productivity inspection

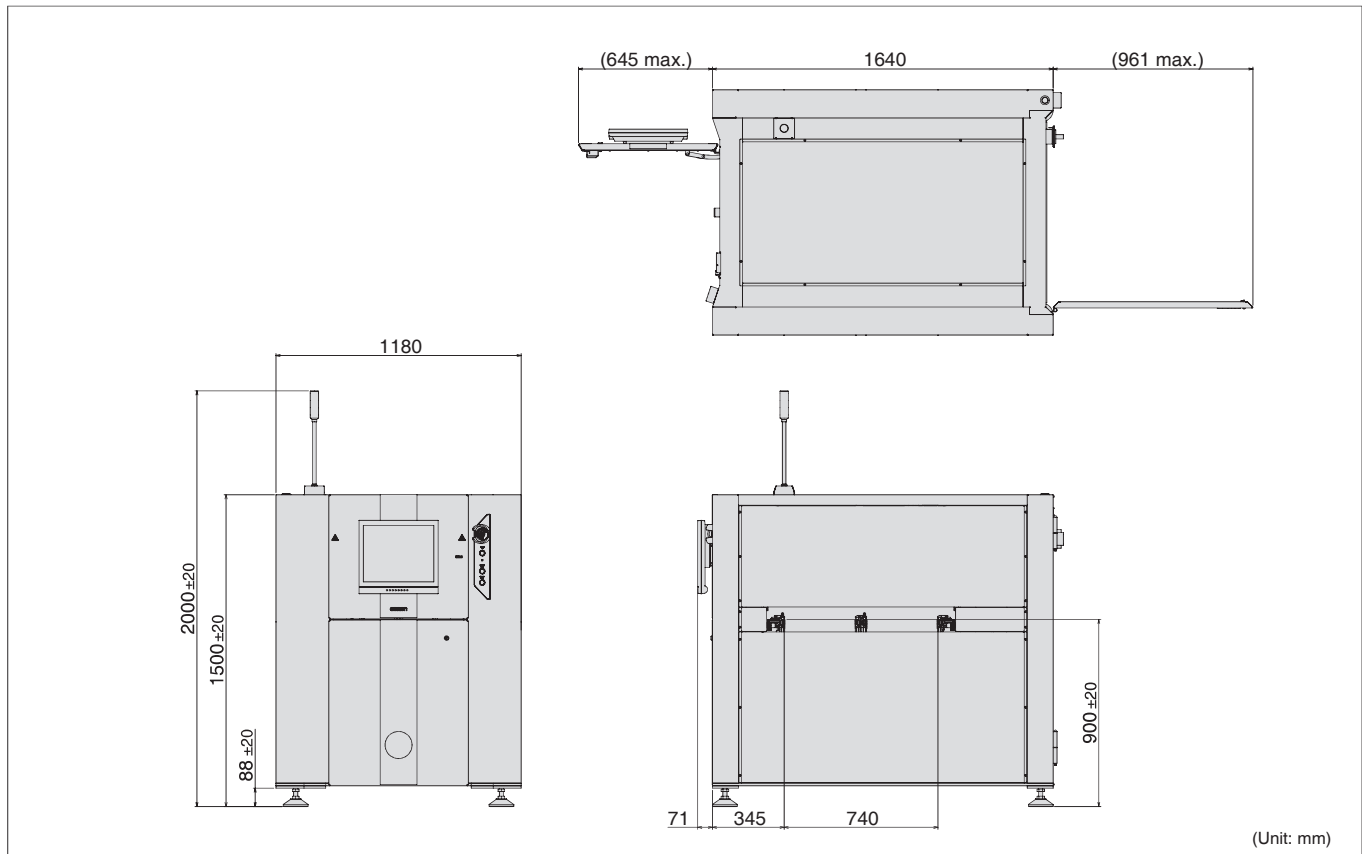
High production throughput supported through dual lane. **Dual lane** operation using various PCBs is possible, due to its handling capability up to the PCB size of 510 (W) x 330 (D) mm.



## System Configuration



## Dimensions



### Hardware configuration

Dimensions		1180(W)×1640 (D)×1500(H) mm
Weight		Approx. 850kg
Power supply	Voltage	200 - 240VAC (single phase), voltage fluctuation range ±10%
	Normal rated power	2.0kVA
Line height		900±20mm
Air supply pressure		0.3 - 0.6MPa
Operating temperature range		10 - 35°C
Operating humidity range		35 - 80%RH (Non-condensing)
Image signal input block	Imaging system	12M pixel camera
	Inspection principle	3D reconstruction through color highlight and phase shift technology
	Image resolution	10µm/15µm
	FOV	10µ: 40×30mm 15µ: 60×45mm

### Functional specifications

Supported PCB size (min.)	50(W)×50(D)mm
Supported PCB size (max.)	Dual lane: 510(W)×330(D)mm
	Single lane: 510(W)×680(D)mm
Clearance	Above: 50mm; Below: 50mm
Height measurement range	25mm
Thickness	0.4 - 4mm
Inspection item	Component height, lift, tilt, missing/wrong component, wrong polarity, flipped component, OCR inspection, 2D code, component offset (X/Y/rotation), fillet (height/length, end joint width, wetting angle, side joint length), exposed land, foreign material, land error, lead offset, lead posture, lead presence, solder ball, solder bridge

- The information provided in this document is mainly for selecting a suitable model. Please read the Instruction Sheet carefully as it contains information regarding warranty, limitations of liability, and precautions. Before purchasing, the user must understand and accept the information presented in the Instruction Sheet.
- This product may cause interference if used in residential areas.

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